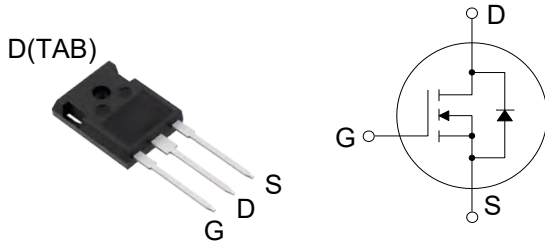


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G=Gate, D=Drain, S=Source, TAB=Drain

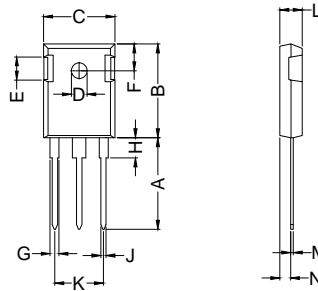
V_{DS} : 1200V

I_D : 31.6A@25°C

$R_{DS(ON)}$: 80mΩ

N Channel Enhancement Mode

Dimensions TO-247AD



Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	19.81	20.32	0.780	0.800
B	20.80	21.46	0.819	0.845
C	15.75	16.26	0.620	0.640
ØD	3.15	3.65	0.124	0.144
E	4.32	5.49	0.170	0.216
F	5.40	6.30	0.213	0.248
G	1.65	2.18	0.065	0.086
H	3.80	4.50	0.150	0.177
J	1.00	1.40	0.039	0.055
K	10.80	11.10	0.425	0.437
L	4.70	5.30	0.185	0.209
M	0.40	0.80	0.016	0.031
N	1.50	2.49	0.059	0.098

Absolute Maximum Ratings (TC=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{DSS}	Drain to Source Voltage	1200	V
V_{GS}	Gate to Source Voltage (DC)	-10 / +25	V
V_{GSop}	Recommended Operation Value	-5 / +20	V
I_D	Drain Current	Continuous ($T_C = 25^\circ\text{C}$)	31.6
		Continuous ($T_C = 100^\circ\text{C}$)	21
I_{DM}	Drain Current	Pulsed (Note1)	80
P_D	Power Dissipation	($T_C = 25^\circ\text{C}$)	150
		Derate Above 25°C	1.00
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to 175	°C
T_L	Maximum Lead Temperature for Soldering, 1/8" from Case for 10 Seconds	260	°C

※Note 1 : Limited by maximum junction temperature.

Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	1.00	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	

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Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
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Off Characteristics

BV_{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}$	1200			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 1200\text{ V}, V_{GS} = 0\text{ V}$		1	100	μA
		$V_{DS} = 1200\text{ V}, V_{GS} = 0\text{ V}, T_J = 175^\circ\text{C}$		5		
I_{GSS}	Gate-Source Leakage Current	$V_{GS} = +22\text{ V}, V_{DS} = 0\text{ V}$			+100	nA
		$V_{GS} = -10\text{ V}, V_{DS} = 0\text{ V}$			-100	

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 5.0\text{ mA}$	2.0	3.0	4.5	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 20\text{ V}, I_D = 20\text{ A}$		80	98	m Ω
		$V_{GS} = 20\text{ V}, I_D = 20\text{ A}, T_J = 150^\circ\text{C}$		150	200	
g_{fs}	Transconductance	$V_{DS} = 20\text{ V}, I_D = 20\text{ A}$		9.8		S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 800\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$		885		pF
C_{oss}	Output Capacitance			65		
C_{rss}	Reverse Capacitance			5		
E_{oss}	Stored Energy in Output Capacitance	$V_{DS} = 0\text{ V to } 800\text{ V}, V_{GS} = 0\text{ V}$		26		μJ
$C_{o(er)}$	Energy Related Output Capacitance			81		pF
$C_{o(tr)}$	Time Related Output Capacitance			142		
$Q_{g(tot)}$	Total Gate Charge	$V_{DS} = 800\text{ V}, I_D = 15\text{ A},$ $V_{GS} = -5\text{ V} / 18\text{ V},$ Inductive load		52		nC
Q_{gs}	Gate to Source Charge			13		
Q_{gd}	Gate to Drain "Miller" Charge			17		
R_G	Internal Gate Resistance	$f = 1\text{ MHz}, V_{AC} = 30\text{ mV}$		4.0		Ω

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DS} = 800\text{ V}, I_D = 15\text{ A},$ $V_{GS} = -5\text{ V} / 18\text{ V}, R_G = 2\text{ }\Omega,$ Inductive load		14		ns
t_r	Turn-On Rise Time			9		
$t_{d(off)}$	Turn-Off Delay Time			24		
t_f	Turn-Off Fall Time			8		
E_{on}	Turn-on Switching Energy			75		μJ
E_{off}	Turn-off Switching Energy			47		
E_{tot}	Total Switching Energy			122		



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Source-Drain Diode Characteristics

I_S	Maximum Continuous Diode Forward Current			30	A
I_{SM}	Maximum Pulsed Diode Forward Current			80	
V_{SD}	Diode Forward Voltage	$V_{GS} = -5\text{ V}, I_{SD} = 15\text{ A}$		4.1	V
t_{rr}	Reverse Recovery Time	$V_{DD} = 800\text{ V}, I_{SD} = 15\text{ A},$ $di_F/dt = 1000\text{ A}/\mu\text{s},$ Includes Q_{oss}		12	ns
Q_{rr}	Reverse Recovery Charge			122	nC

FEATURES

- * High switching speed with a low gate charge
- * Fast intrinsic diode with low reverse recovery
- * Robust Avalanche Capability
- * 100% Avalanche Tested
- * Plastic package has UL flammability classification 94V-0
- * RoHS compliant

MECHANICAL DATA

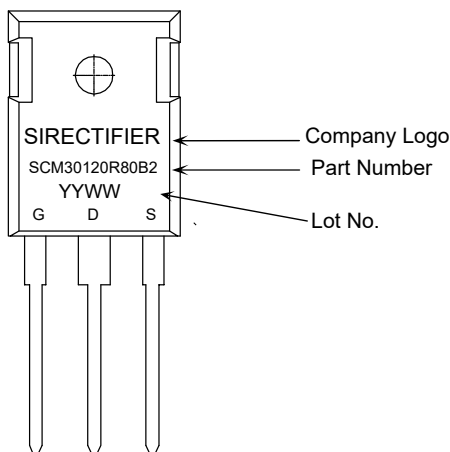
- * Case: TO-247AD molded plastic
- * Polarity: As marked on the body
- * Weight: 6 grams
- * Mounting position: Any

APPLICATIONS

- * Solar inverter
- * EV charging station
- * UPS
- * Industrial power supply



MARKING



ORDERING INFORMATION

Part Number	Package	Shipping	Marking Code
SCM30120R80B2	TO-247AD	30pcs / Tube	SCM30120R80B2

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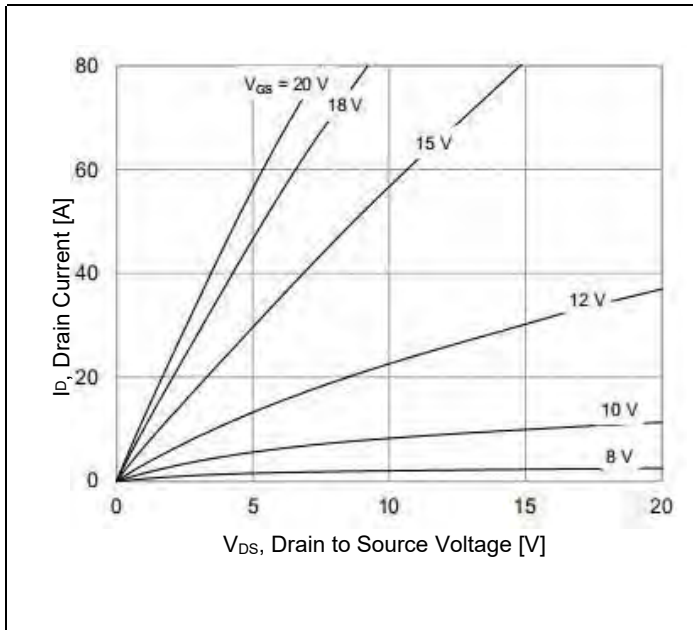


Figure 1. On-Region Characteristics $T_J = -40^\circ\text{C}$

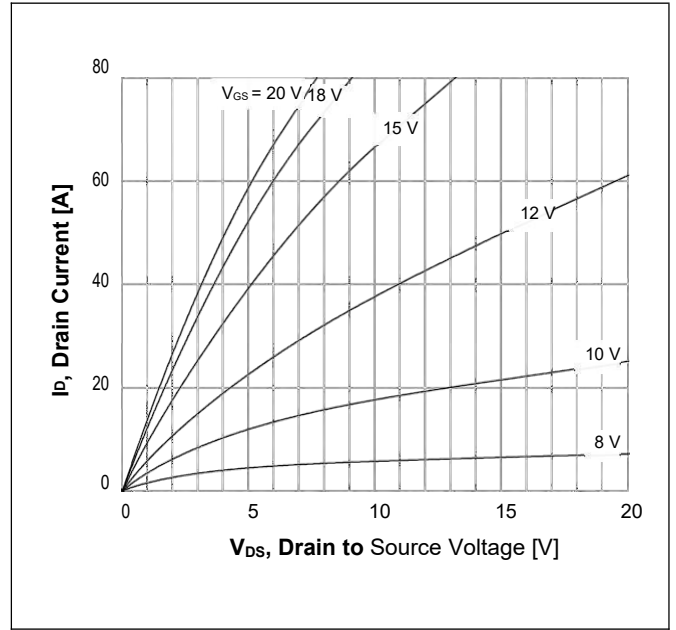


Figure 2. On-Region Characteristics $T_J = 25^\circ\text{C}$

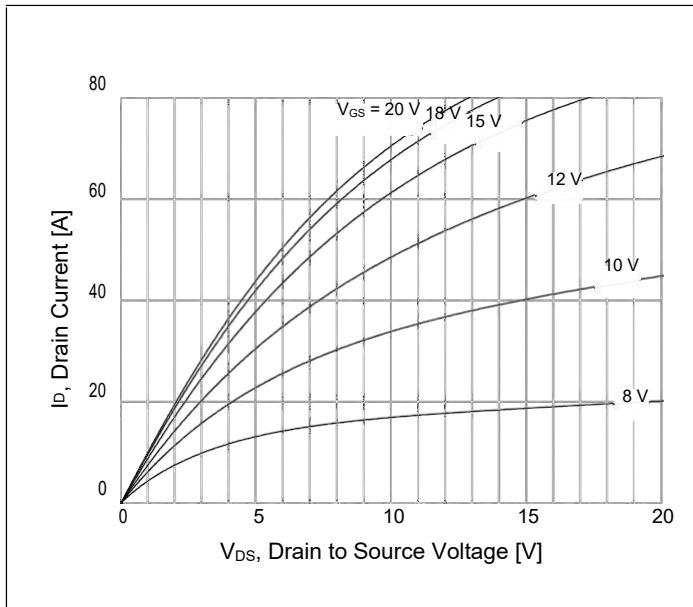


Figure 3. On-Region Characteristics $T_J = 175^\circ\text{C}$

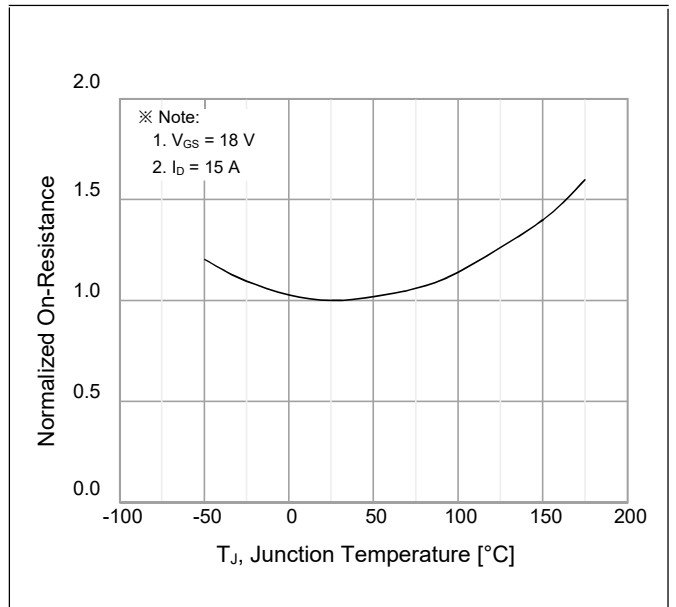


Figure 4. Normalized On-Resistance Characteristics vs. Temperature

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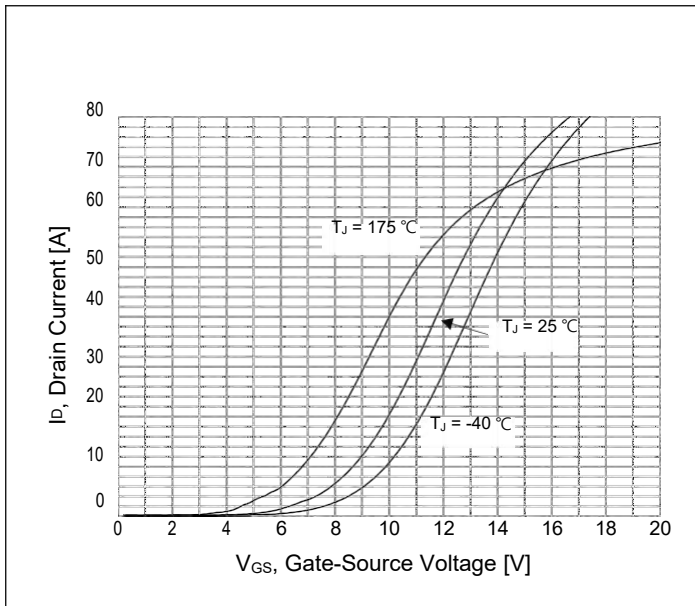


Figure 5. Transfer Characteristics

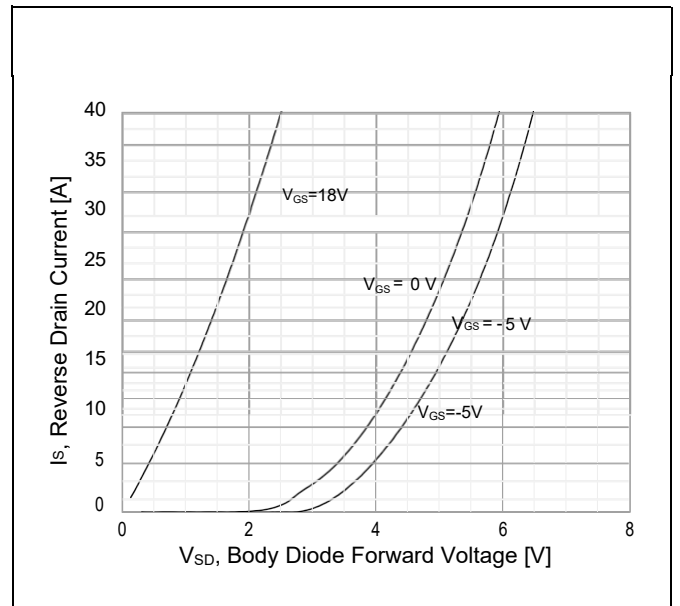


Figure 6. Diode Forward Voltage Characteristics vs. Source-Drain Current $T_J = -40^\circ\text{C}$

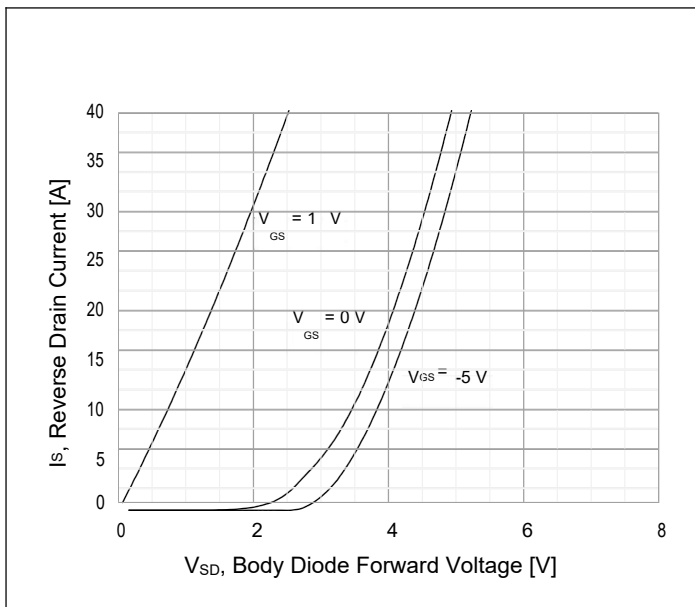


Figure 7. Diode Forward Voltage Characteristics vs. Source-Drain Current $T_J = 25^\circ\text{C}$

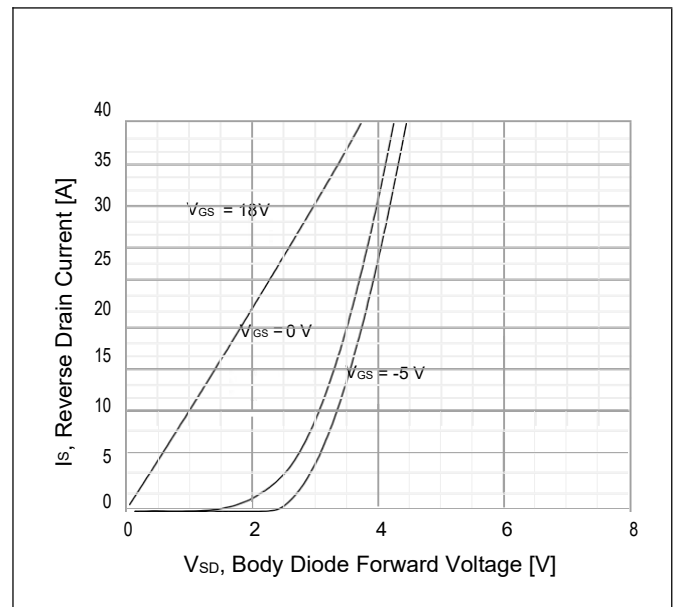


Figure 8. Diode Forward Voltage Characteristics vs. Source-Drain Current $T_J = 175^\circ\text{C}$

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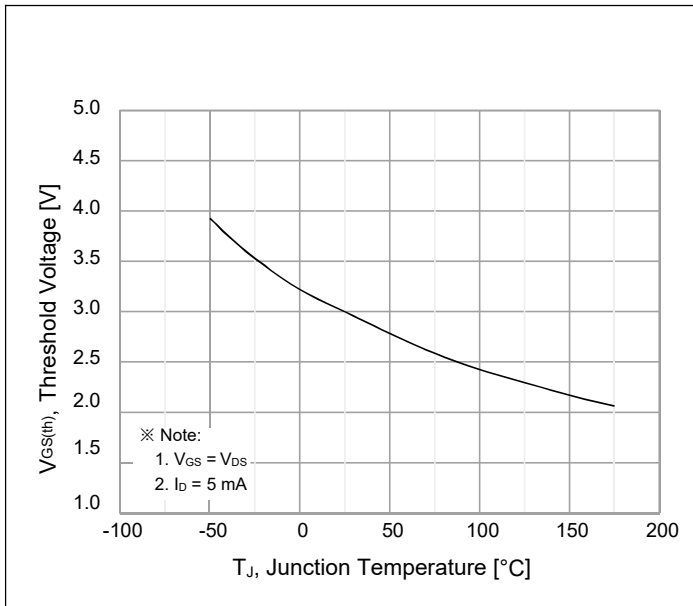


Figure 9. Threshold Voltage vs. Temperature

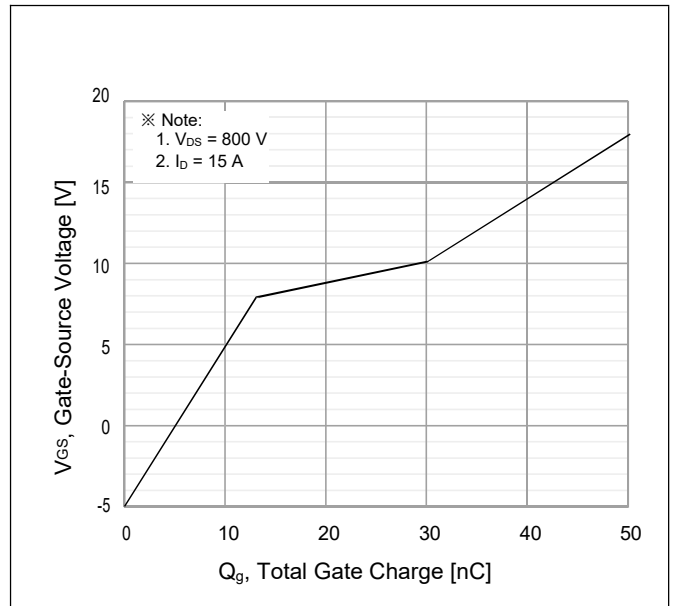


Figure 10. Gate Charge Characteristics

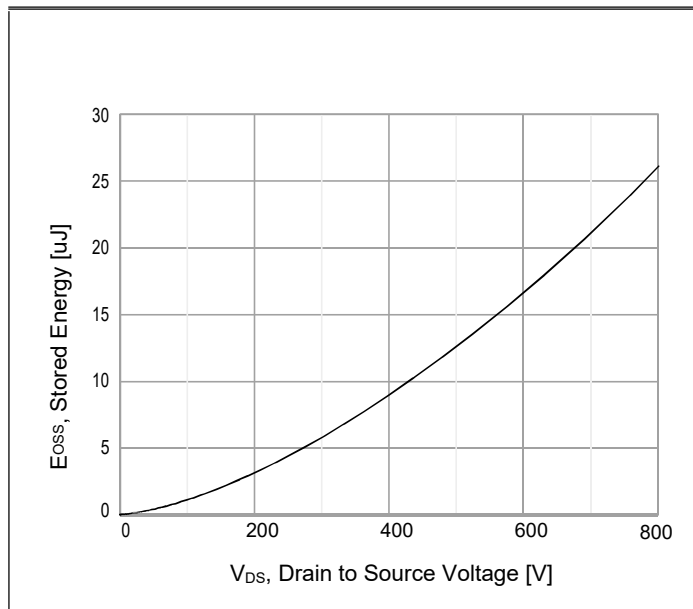


Figure 11. Stored Energy in Output Capacitance

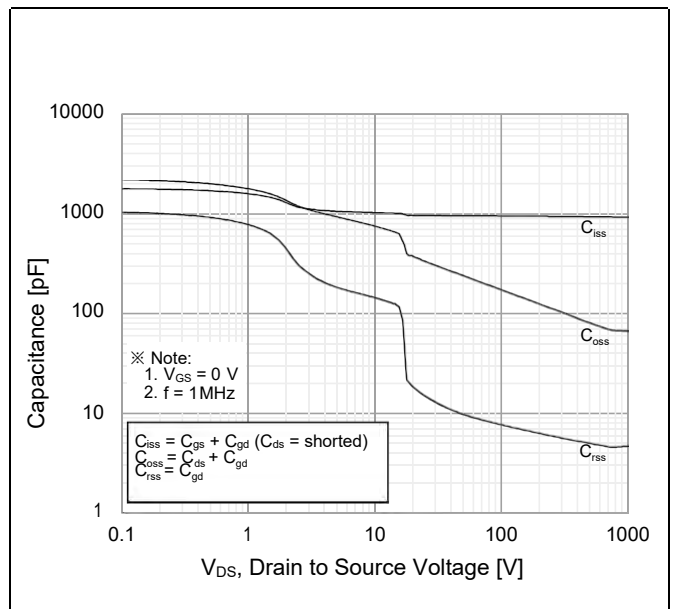


Figure 12. Capacitance Characteristics

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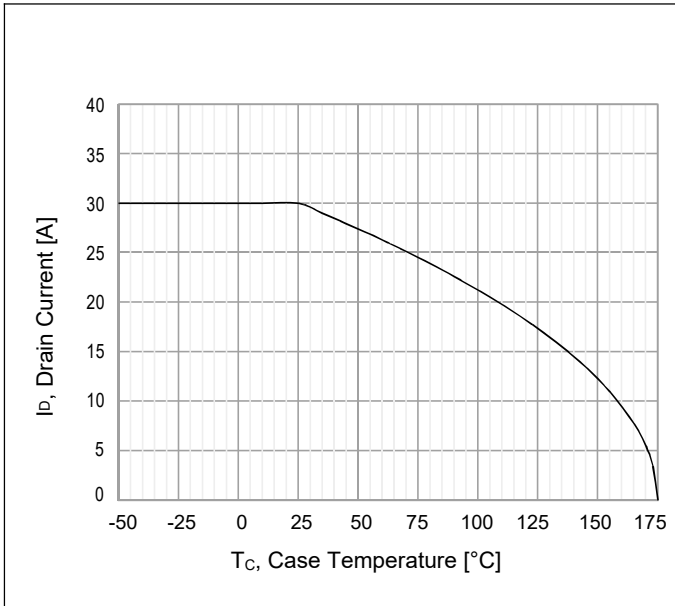


Figure 13. Continuous Drain Current Derating vs. Case Temperature

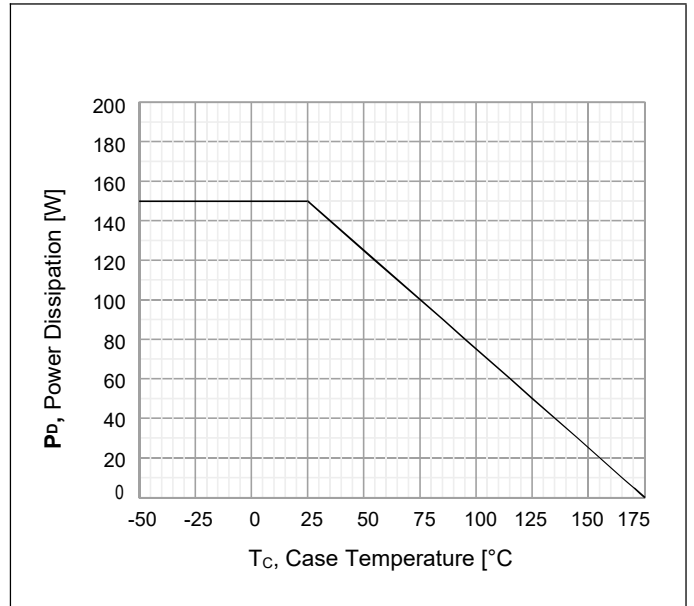


Figure 14. Maximum Power Dissipation Derating vs. Case Temperature

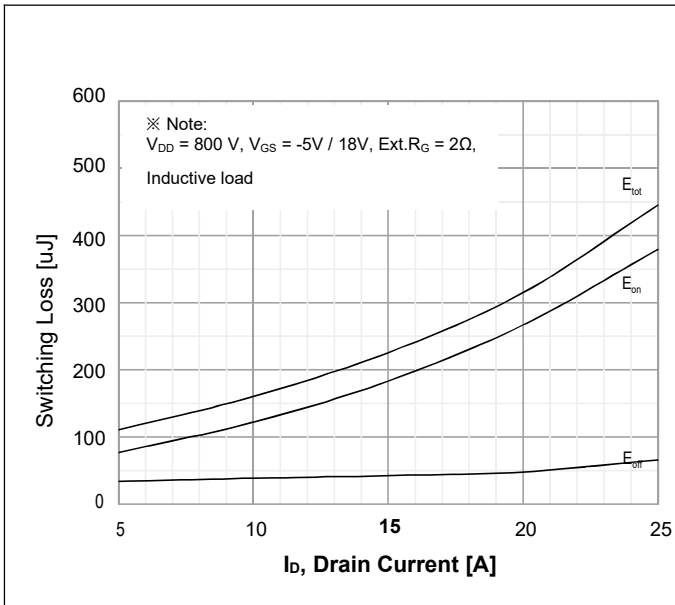


Figure 15. Typ. Switching losses vs. Drain current

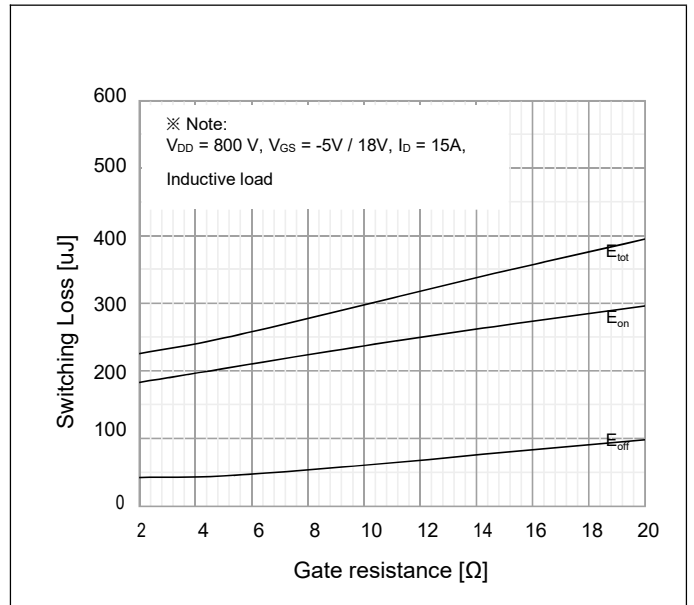


Figure 16. Typ. Switching losses vs. Gate resistance

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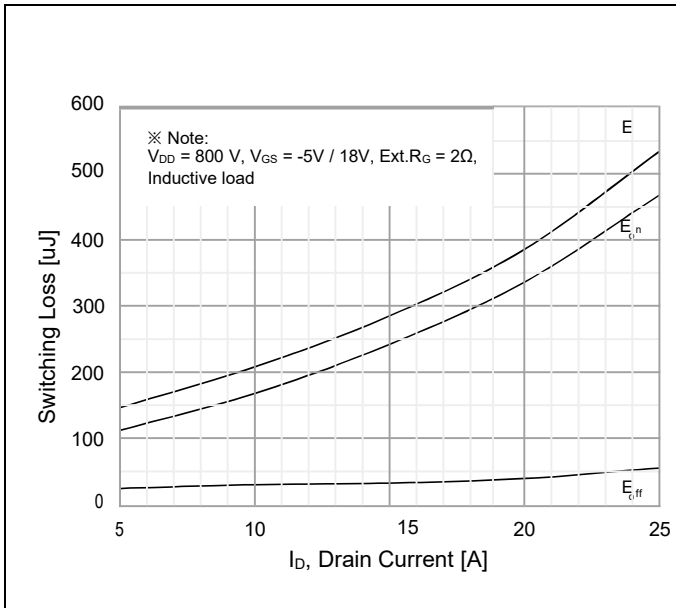


Figure 17. Typ. Switching losses vs. Drain current

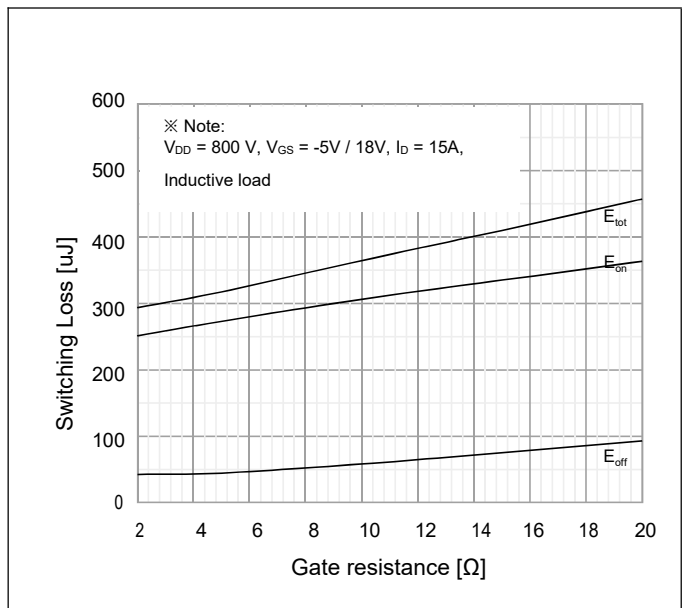


Figure 18. Typ. Switching losses vs. Gate resistance

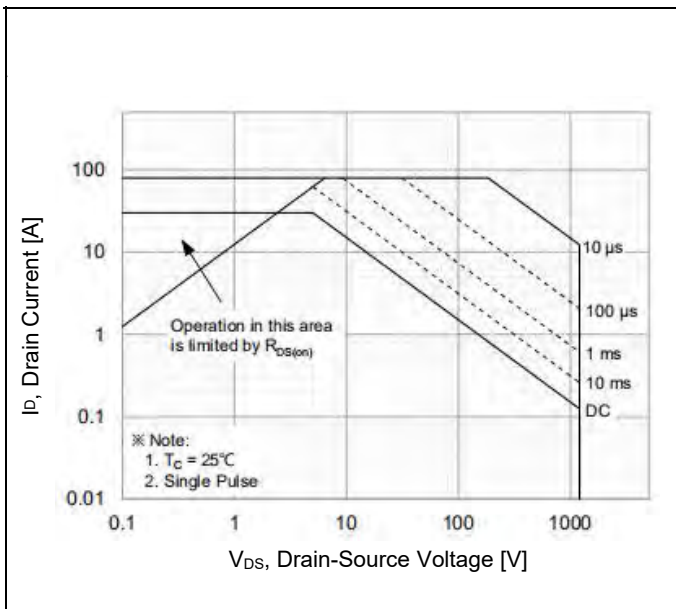


Figure 19. Maximum Safe Operating Area

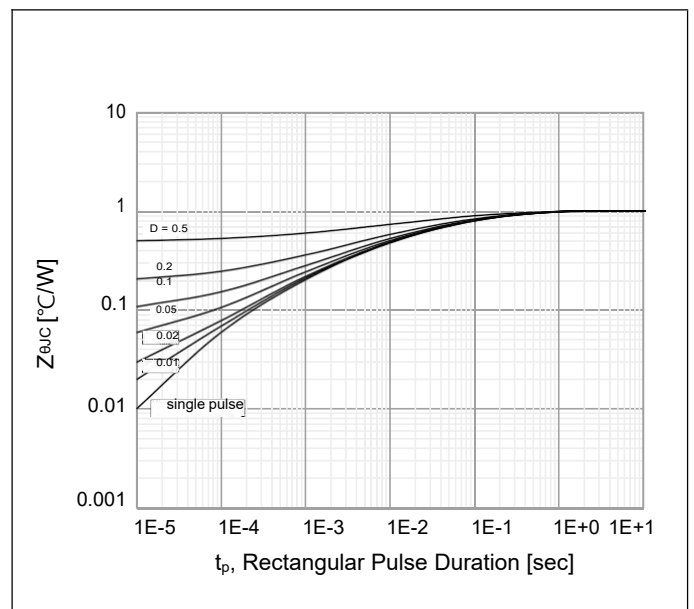


Figure 20. Transient Thermal Response Curve

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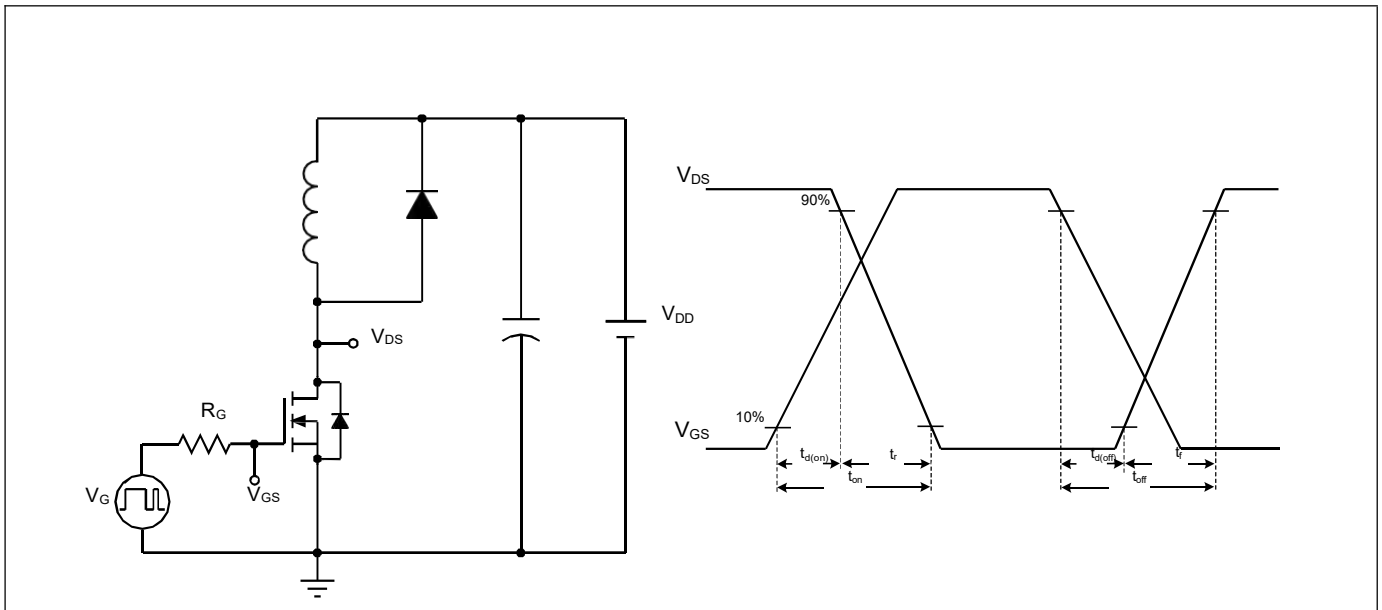


Figure 21. Inductive Load Switching Test Circuit and Waveforms

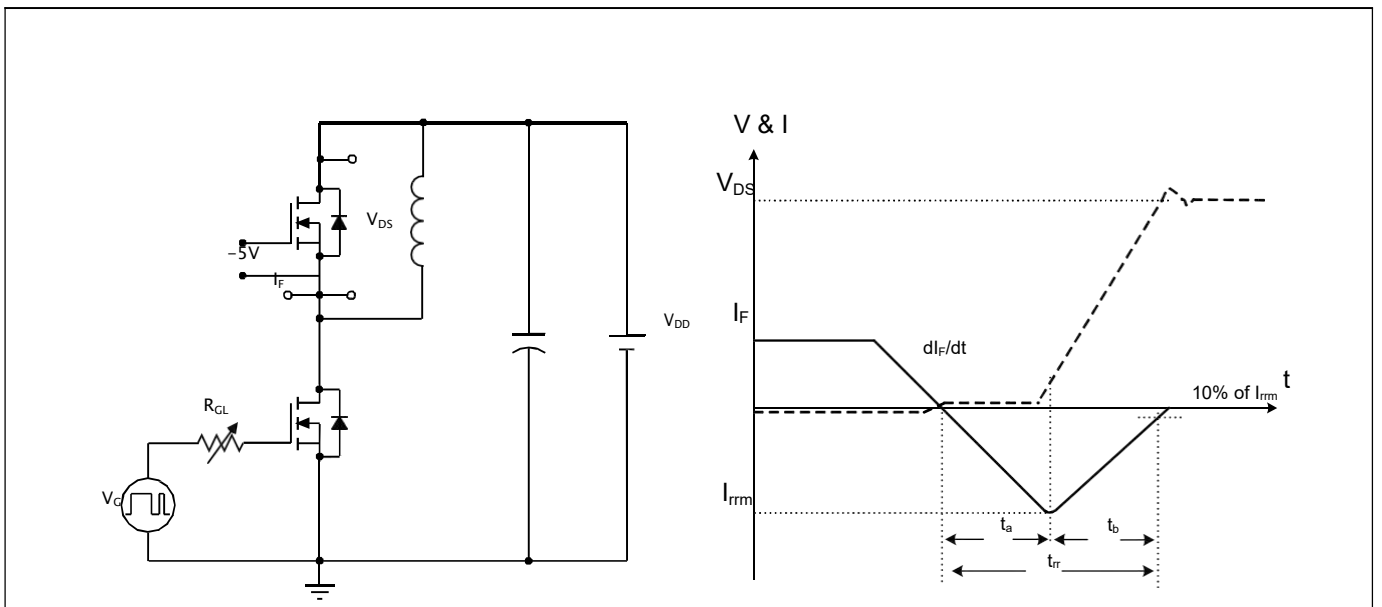


Figure 22. Peak Diode Recovery dv/dt Test Circuit and Waveforms